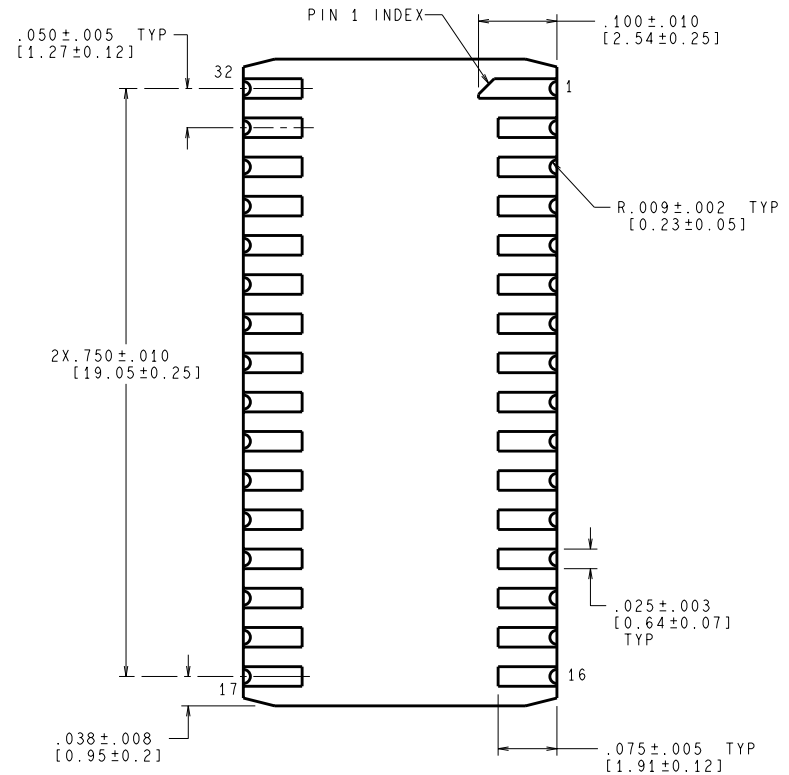
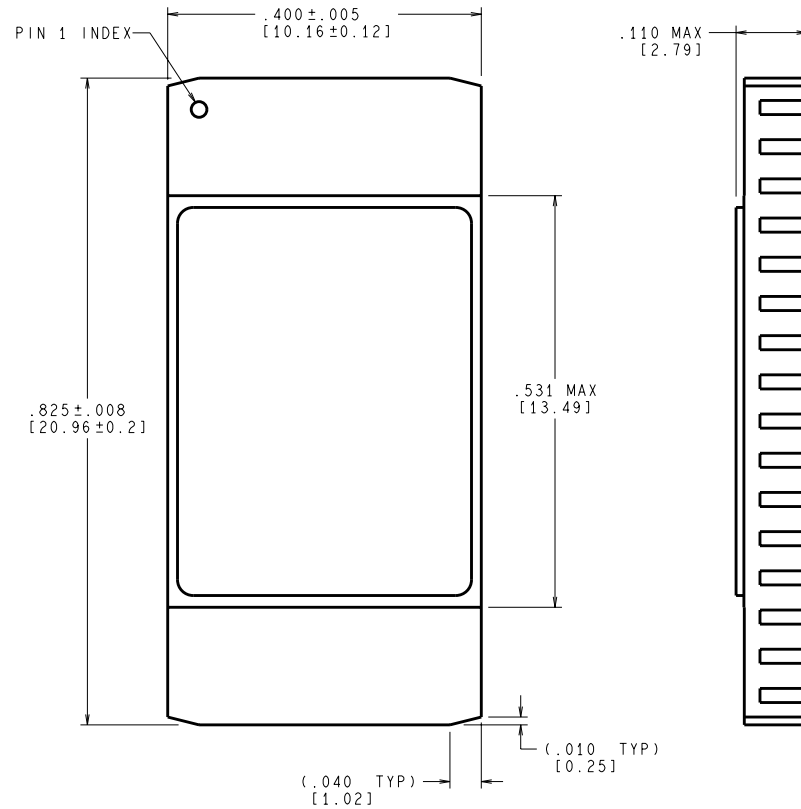


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11938	07/27/1998	TL/



CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:

- 50 MICROINCHES [1.27 MICROMETERS] MINIMUM GOLD PLATING
OVER 50 TO 350 MICROINCHES [1.27 TO 8.89 MICROMETERS] NICKEL.
- SOLDER DIP.
SOLDER THICKNESS PER LATEST REVISION OF MIL-STD-1835.

4. NO REFERENCE JEDEC REGISTRATION AS OF JUNE 1998.

MIL-PRF-38535
CONFIGURATION CONTROL

APPROVALS		DATE		 2900 Semiconductor dr. Santa Clara, CA 95052-8090	
DRAWN T. LEQUANG		07/27/1998			
DFTG. CHK.					
ENGR. CHK.					
 PROJECTION INCH [MM]				SCALE N/A	
SIZE C				DRAWING NUMBER (SC)MKT-EA32D	
DO NOT SCALE DRAWING				REV A	
				SHEET 1 of 1	